

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2043	@ad<="20040301" and (257/717-718).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:03
S2	1319	@ad<="20040301" and (257/706).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:09
S3	714	@ad<="20040301" and (257/720).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:10
S4	812	@ad<="20040301" and (257/675).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:11
S5	147	@ad<="20040301" and (257/625).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:48
S6	163	@ad<="20040301" and (257/276).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:33
S7	625	@ad<="20040301" and (438/122).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:10
S8	1452	@ad<="20040301" and (174/16.3).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:10
S9	176	@ad<="20040301" and (228/222).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:11
S10	18	@ad<="20040301" and (361/274.3).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:11
S11	767	@ad<="20040301" and (361/697).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:07

S12	341	@ad<="20040301" and (361/702). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:11
S13	671	@ad<="20040301" and (361/709). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:12
S14	11	@ad<="20040301" and (361/514). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:12
S15	439	@ad<="20040301" and 'thermal' with 'electrical' and 'semiconductor body'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:35
S16	16	@ad<="20040301" and 'thermal' with 'electrical' and 'semiconductor body' and 'trough'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:36
S17	0	@ad<="20040301" and 'heat sink' same ('SiC' or 'diamond') and 'semiconductor body' and 'trough'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:37
S18	28	@ad<="20040301" and 'heat sink' same ('SiC' or 'diamond') and 'semiconductor body'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:45
S19	169	@ad<="20040301" and 'thermo-electrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:12
S20	22	@ad<="20040301" and 'thermo-electrical' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:13
S21	0	@ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive' and 'heat transfer' same 'helix'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:08
S22	0	@ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive' and 'heat transfer' same 'maze'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:07

S23	0	@ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive' and 'heat transfer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:07
S24	0	@ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:07
S26	5	@ad<="20040301" and 'semiconductor' and 'heat sink' and 'conductive' and 'heat transfer' same 'helix'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:09
S27	7	@ad<="20040301" and 'semiconductor' and 'heat sink' and 'conductive' and 'heat transfer' same 'maze'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:11
S28	4	@ad<="20040301" and 'heat regulating' and 'semiconductor' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:17
S29	0	@ad<="20040301" and 'heat regulating device' and 'IC' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:17
S30	0	@ad<="20040301" and 'heat regulating' and 'IC' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:18
S31	7	@ad<="20040301" and 'heat regulating' and 'chip' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:19
S32	0	@ad<="20040301" and 'heat regulating device' same 'maze'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:20
S33	0	@ad<="20040301" and 'heat regulating device' same 'helix'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:44
S34	55	@ad<="20040301" and 'heat sink' same 'helix'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:25

S35	8	@ad<="20040301" and 'heat sink' same 'maze'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:32
S36	9	@ad<="20040301" and 'heat sink' same 'helix' and 'semiconductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:25
S37	0	@ad<="20040301" and 'thermal' with 'regulating' same 'semiconducotr' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:46
S38	0	@ad<="20040301" and 'thermal' with 'control' same 'semiconducotr' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:46
S39	0	@ad<="20040301" and 'heat' with 'control' same 'semiconducotr' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:46
S40	4	@ad<="20040301" and 'thermal' with 'regulating' same 'semiconductor' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:46
S41	737	@ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'semiconductor' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:47
S42	220	@ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'semiconductor device' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:47
S43	145	@ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'IC' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:48
S44	424	@ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'chip' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:48
S45	1508	@ad<="20040301" and (361/695). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:21

S46	144	@ad<="20040301" and (361/696). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:07
S47	1	"6016250".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:07
S48	1	"5773755".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:07
S49	1	"5463529".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:08
S51	181	@ad<="20040301" and ('array' or 'matrix') with 'heat sink' same 'semiconductor device'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:16
S52	24	@ad<="20040301" and 'matrix' with 'heat sink' same 'semiconductor device'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:20
S53	522	@ad<="20040301" and 'matrix' with 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:20
S54	394	@ad<="20040301" and (361/694). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:21
S55	1	"5988488".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:26
S56	1	"5848467".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:26
S57	1162	@ad<="20040301" and (257/718). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:28
S58	952	@ad<="20040301" and (257/717). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:28
S59	711	@ad<="20040301" and (257/718). ccls. and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:28
S60	283	@ad<="20040301" and (257/718). ccls. and 'heat sink' same 'semiconductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:29

S61	5	@ad<="20040301" and 'maze' with 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:42
S62	20	@ad<="20040301" and 'helix' with 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:32
S63	35	@ad<="20040301" and 'thermal control' with 'IC'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:32
S64	1	"6016250".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:47
S65	943	@ad<="20040301" and (257/719). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:08
S67	1	@ad<="20040301" and (257/719). ccls. and 'heat' same dissipat\$4 same 'silicon carbide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:06
S68	32	@ad<="20040301" and (257/719). ccls. and 'diamond'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:16
S71	1	@ad<="20040301" and 'therm' with 'sensor' and ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:19
S75	45	@ad<="20040301" and 'semiconductor' and ('thermal' or 'thermo') with 'electrical' same 'heat flow' and ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:22
S76	1	"5712448".PN.	USPAT; USOCR	OR	ON	2005/12/27 09:26
S77	1	"5705770".PN.	USPAT; USOCR	OR	ON	2005/12/27 09:26
S78	143	@ad<="20040301" and 'thermal control' with 'semiconductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:33
S79	35	@ad<="20040301" and 'thermal control' with 'ic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:35

S80	2	@ad<="20040301" and 'Controlling hot spots' and ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:36
S81	124	@ad<="20040301" and 'semiconductor' same 'hot spots' and ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:49
S82	1	"6521991".PN.	USPAT; USOCR	OR	ON	2005/12/27 09:39
S83	1	"6334311".PN.	USPAT; USOCR	OR	ON	2005/12/27 09:40
S84	1	"6322626".PN.	USPAT; USOCR	OR	ON	2005/12/27 09:41
S85	1	"6199927".PN.	USPAT; USOCR	OR	ON	2005/12/27 09:41
S86	13	@ad<="20040301" and 'semiconductor' same 'hot spots' same ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:08
S87	2	@ad<="20040301" and 'semiconductor' same 'thermo-electric' same ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:09
S88	141	@ad<="20040301" and 'semiconductor' and 'thermo-electric' and ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:10
S89	7	@ad<="20040301" and 'semiconductor' and 'thermo-electric' same ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:10
S90	12	@ad<="20040301" and 'semiconductor' same 'thermo-electric' and ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:11
S91	171	@ad<="20040301" and 'thermo-electrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:12
S92	23	@ad<="20040301" and 'thermo-electrical' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:14

S93	776	@ad<="20040301" and 'thermo' with electric\$2 and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:13
S94	501	@ad<="20040301" and 'thermo-electric' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:34
S95	1	@ad<="20040301" and 'thermo-electric' and 'heat sink' same 'silicon carbide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:14
S96	27	@ad<="20040301" and 'thermo-electric' and 'heat sink' and 'silicon carbide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:26
S97	74	@ad<="20040301" and 'thermo-electric' and 'heat sink' and ('silicon carbide' or 'diamond')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:26
S98	9	@ad<="20040301" and 'thermo-electric' and 'heat sink' same 'diamond'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:30
S99	1	@ad<="20040301" and 'thermo-electric' and 'heat sink' same 'carbide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:35
S10 0	27	@ad<="20040301" and 'thermo-electric' and 'heat sink' and 'silicon carbide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:45
S10 1	4	(("6098408") or ("5940784")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/27 10:45
S10 2	1	"5940784".PN.	USPAT; USOCR	OR	ON	2005/12/27 10:47
S10 3	1	"5867990".PN.	USPAT; USOCR	OR	ON	2005/12/27 10:47
S10 4	410	@ad<="20040301" and (62/3.7). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:48



S10 5	1	"5822993".PN.	USPAT; USOCR	OR	ON	2005/12/27 10:48
S10 6	1	"5867990".PN.	USPAT; USOCR	OR	ON	2005/12/27 10:48
S10 7	1	"5690849".PN.	USPAT; USOCR	OR	ON	2005/12/27 10:49